IPC ASSOCIATION CON ELECTRONICS IND	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both leve	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information				
upplier In	formation						·							
Company name*			Company unique ID			U	Unique ID Authority				Response Date*			
nsemi										2025-06-07				
Contact Name	2	Title - Contact			Pl	Phone - Contact*				Email - Contact*				
Product-Env-	-Stewards		Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com			
uthorized Re	epresentative*		Title - Representative			Pl	Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com			
Re	equester Item Number	Mfr Item Number		Mfr Item Name		I	Effective Date	Version	Mai	Manufacturing Site		Veight*	UOM	Unit Type
		NRVBSS25FA 50V 2A Schot		50V 2A Schottky R	Rectif		2025-06-07 TSCBE		СВЕ	19.0		mg	Each	
Ianufactu	ring Proccess Informa	ation												
Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-S	STD-020 MSL Ra	SL Rating Peak Process Body Temperature Max Time at Peal				k Temperature Number of Reflow Cycles					
Ma	tte Tin (Sn) - annealed	(CU Alloy	1			260	C		30	second	ls 3		
omments														
vel 1 - maxin	num time at peak temperat	ture during sol	dering is 10-3	30 seconds										
or more info	rmation regarding materia	l composition	please refer t	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to suc										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.8113	mg	Supplier	Titanium (Ti)	7440-32-6		0.0012	mg
			Supplier	Silver (Ag)	7440-22-4		0.0302	mg
			Supplier	Silicon (Si)	7440-21-3		0.7724	mg
			В	Nickel (Ni)	7440-02-0		0.0075	mg
Die Attach Solder	1.67086	mg	Supplier	Silver (Ag)	7440-22-4		0.0418	mg
			A	Lead (Pb)	7439-92-1	7a	1.5455	mg
			Supplier	Tin (Sn)	7440-31-5		0.0835	mg
Lead Frame	7.25648	mg	Supplier	Iron (Fe)	7439-89-6		0.0073	mg
			Supplier	Copper (Cu)	7440-50-8		7.247	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0022	mg
Mold Compound-Black	9.07041	mg		Metal Hydroxide	proprietary data		0.4535	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0907	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6.8028	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.907	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.8163	mg
Plating	0.19095	mg	Supplier	Tin (Sn)	7440-31-5		0.191	mg